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**ABSTRACT OF THE DISCLOSURE**

There is provided a structure for connecting substrates to each other, which is capable of thinning an electronic device on which a plurality of circuit boards is mounted, saving a space of the electronic device, and detaching a circuit board from the electronic device. The circuit board unit includes a first substrate including, on a surface thereof, a first group of electrode terminals arranged in a matrix, a second substrate including, on a surface thereof, a second group of electrode terminals arranged in a matrix in alignment with the first group of electrode terminals, and an anisotropic electrical conductor sandwiched between the first and second substrates. The first and second substrates and the anisotropic electrical conductor are pressurized by means of a pressurizer to electrically connect the electrode terminals to each other through the anisotropic electrical conductor.